**Product End-of-Life Disassembly Instructions**

**Product Category:** External Options Monitor and Display

**Marketing Name / Model**
[List multiple models if applicable.]

HP V22 FHD Monitor

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain.</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>power cable, HDMI cable</td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

EL-MF877-00
Template Revision C

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service</td>
<td>0</td>
</tr>
<tr>
<td>(gel/paste) and toner</td>
<td>stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(HEX HEAD)</td>
<td>5mm</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove cable from Display head
2. Remove Stand Base From Display Head
3. Remove Rear Cover From Display Head
4. Remove Acetate Tape and EMI From Display Head
5. Remove LED Cable ,Interface Cable and Osd Cable From Display Head
6. Remove Bracket Assy From Display Head
7. Remove Panel Assy From Display Head
8. Remove Interface BD and Power BD From Bracket Assy
9. Remove Base and Rubber From Stand ASSY
10. Remove Hinge From Stand Assy
11. Remove Wall Mount From Rear Cover
12. Disassemble Panel Assy

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

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HPI instructions for this template are available at [EL-MF877-01](EL-MF877-01)
V22 Disassemble Process

Prepare By: Chaim Liang
Date : 2020/03/04
1. Remove cable from display head
2. Remove Stand Base From Display Head

2. Push the red point

3. Remove stand base assembly
3. Remove Rear Cover From Display Head

4. Release the five screw from rear cover

#2 cross screwdriver

5. Pull up front cover
3. Remove Rear Cover From Display Head

6. Pull up rear cover

7. Remove rear cover
4. Remove Acetate Tape And EMI From Display Head

8. Remove acetate tape and EMI
5. Remove Cable From Display Head

9. Remove LED, OSD and LVDS cable
6. Remove Bracket Assembly From Display Head

10. Remove the screw from bracket

11. Remove bracket assembly
7. Remove Panel Assembly From Display Head

12. Remove panel assembly
8. Remove Interface And Power BD From Bracket Assembly

13. Release the two screw from bracket

14. Release the four screw from BD

15. Remove interface and power BD from
9. Remove Base And Rubber From Stand Assembly

16. Remove base and rubber
10. Remove Hinge From Stand Assembly

17. Release the four screws from the stand by screwdriver

18. Remove hinge
11. Remove Wall Mount From Rear Cover

19. Remove wall mount
**12. Disassemble Panel Assembly**

**M215HTN01.1 Panel 拆解图**

<table>
<thead>
<tr>
<th>LCD disassembly description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1. Remove all PCBA screws</td>
</tr>
<tr>
<td>2. Remove front bezel</td>
</tr>
<tr>
<td>3. Remove TFT glass &amp; PCBA</td>
</tr>
</tbody>
</table>

<p>| | |</p>
<table>
<thead>
<tr>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>4. Remove plastic frame</td>
<td>5. Remove optical films</td>
</tr>
<tr>
<td></td>
<td>6. Lift light guide plate and remove LED assembly</td>
</tr>
</tbody>
</table>

19. Disassemble panel assembly
12. Disassemble Panel Assembly

LM215DT7A41: Disassembly Method

Disassembly (1-2)

1. Mylar
2. Bezel
3. Panel Glass
4. Frame
5. Sheets

Removing a Mylar
Removing a Bezel
Removing a Panel Glass
Removing a Frame
Removing Sheets

19. Disassemble panel assembly
12. Disassemble Panel Assembly

LM215DT7A41: Disassembly Method

Disassembly (2-2)

6. Removing a LGP

7. Removing a Reflection Sheet

8. Removing a LED Bar

LED Bar is fixed with a tape, so we need to take off well with any flat things.

19. Disassemble panel assembly
Thank You !!!